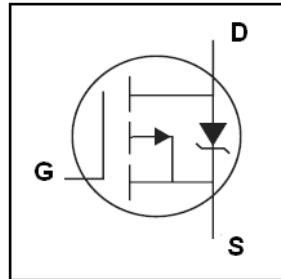


Features

- ◆ $R_{on}(\text{typ.})=55\text{ m}\Omega$
- ◆ Low On-Resistance
- ◆ 150°C Operating Temperature
- ◆ Fast Switching
- ◆ Lead-Free, RoHS Compliant
- ◆ Green Product



$V_{DSS} \geq -30\text{V}$
 $R_{DS(on)}=55\text{ m}\Omega @ V_{GS}=-10\text{V}$
 $R_{DS(on)}=65\text{ m}\Omega @ V_{GS}=-4.5\text{V}$
 $I_D = -4.2\text{ A} @ V_{GS}=-10\text{V}$

Description

VS3401AT-G designed by the trench processing techniques to achieve extremely low on-resistance. And fast switching speed and improved transfer effective . These features combine to make this design an extremely efficient and reliable device for variety of DC-DC applications.



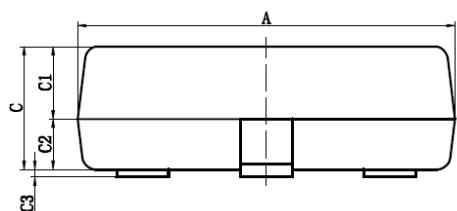
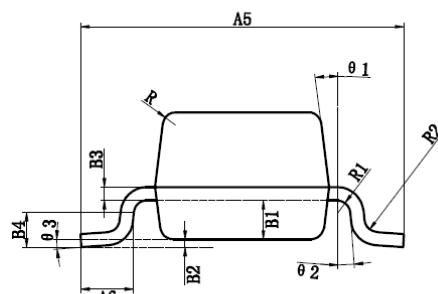
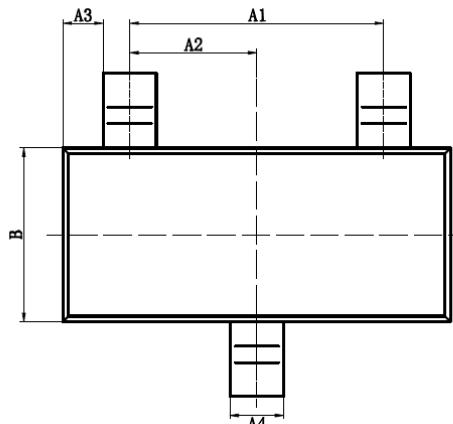
Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (TA) is 25°C, unless otherwise specified.

Symbol	Parameter	Rating	Unit
Common Ratings ($T_c=25^\circ\text{C}$ Unless Otherwise Noted)			
V_{GS}	Gate-Source Voltage	± 12	V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	-30	V
T_J	Maximum Junction Temperature	150	°C
T_{STG}	Storage Temperature Range	-50 to 155	°C
I_s	Diode Continuous Forward Current	$T_c=25^\circ\text{C}$	-4.2 ^①
Mounted on Large Heat Sink			
I_{DM}	Pulse Drain Current Tested	$T_c=25^\circ\text{C}$	-16.8
I_D	Continuous Drain Current($V_{GS}=10\text{V}$)	$T_c=25^\circ\text{C}$	-4.2 ^①
		$T_c=100^\circ\text{C}$	-3.2
P_D	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	1.3
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	120	°C/W

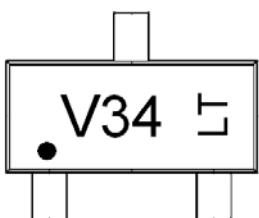
Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ $I_D=-250\mu\text{A}$	-30	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current ($T_c=25^\circ\text{C}$)	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-1	μA
	Zero Gate Voltage Drain Current ($T_c=125^\circ\text{C}$)	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 12\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS(TH)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_D=-250\mu\text{A}$	-0.5	-0.7	-1.5	V
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=-10\text{V}, I_D=-4.2\text{A}$	--	55	75	$\text{m}\Omega$
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=-4.5\text{V}, I_D=-4.0\text{A}$	--	65	90	$\text{m}\Omega$
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=-2.5\text{V}, I_D=-1.0\text{A}$	--	85	120	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	--	710	--	pF
C_{oss}	Output Capacitance		--	90	--	pF
C_{rss}	Reverse Transfer Capacitance		--	40	--	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=-15\text{V}, I_D=-4.0\text{A}, V_{\text{GS}}=-4.5\text{V}$	--	8.5	--	nC
Q_{gs}	Gate-Source Charge		--	0.9	--	nC
Q_{gd}	Gate-Drain Charge		--	1.7	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=-15\text{V}, I_D=-4\text{A}, R_G=6\Omega, V_{\text{GS}}=-4.5\text{V}, R_L=5\Omega$	--	8.5	--	nS
t_r	Turn-on Rise Time		--	5.5	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	26	--	nS
t_f	Turn-Off Fall Time		--	12.5	--	nS
Source- Drain Diode Characteristics						
I_{SD}	Source-drain current(Body Diode)	$T_c=25^\circ\text{C}$	--	--	-4.2 ^①	A
V_{SD}	Forward on voltage	$T_j=25^\circ\text{C}, I_{\text{SD}}=-4\text{A}, V_{\text{GS}}=0\text{V}$	--	-0.85	-1.3	V

Notes: ① Pulse test ; Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.



尺寸 标注	最小 (mm)	最大 (mm)	尺寸 标注	最小 (mm)	最大 (mm)
A	2.80	3.00	B4	0.90	0.975
A1	1.80	2.00	C	0.535	0.585
A2	0.95TYP		C1	0.365	0.415
A3	0.20	0.40	C2	0.01	0.11
A4	0.30	0.50	C3	0.24	0.254TYP
A5	2.34	2.50	R	0.11TYP	
A6	0.30	0.60	R1	0.11TYP	
B	1.25	1.35	R2	0.11TYP	
B1	0.265	0.315	θ1	6° ~ 8° TYP4	
B2	0.01	0.11	θ2	5° REF	
B3	0.10TYP		θ3	1° ~ 7°	

Marking



Part Name Code:V34
Lot Code:LT (From 00 to ZZ)
GP Mark: ●

Order Information

Product	Marking	Package	Packaging	Min Unit Quantity
VS3401AT-G	V34	SOT23	3000/Reel	6000

Customer Service

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